

## 2.5V Drive Nch MOSFET

## ● Structure

## TY N-channel MOSFET

## ● Features

- 1) Low On-resistance.
  - 2) Built-in G-S Protection Diode.
  - 3) Small Surface Mount Package (TSMT3).

#### •Application

Switching

#### ●Packaging specifications

Type	Package	Taping
		TL
Basic ordering unit (pieces)		3000
RTR025N05		○

#### ● **Absolute maximum ratings** ( $T_a=25^\circ\text{C}$ )

Parameter	Symbol	Limits	Unit	
Drain-source voltage	V <sub>DSS</sub>	45	V	
Gate-source voltage	V <sub>GSS</sub>	±12	V	
Drain current	Continuous	I <sub>D</sub>	±2.5	A
	Pulsed	I <sub>DP</sub>	*1 ±10	A
Source current (Body diode)	Continuous	I <sub>S</sub>	0.8	A
	Pulsed	I <sub>SP</sub>	*1 10	A
Total power dissipation	P <sub>D</sub>	*2 1.0	W	
Channel temperature	T <sub>CH</sub>	150	°C	
Range of Storage temperature	T <sub>STG</sub>	-55 to +150	°C	

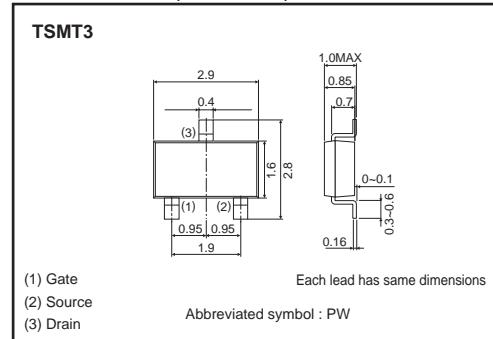
\*1 Pw≤10μs, Duty cycle≤1%  
\*2 When mounted on a ceramic board

### ● Thermal resistance

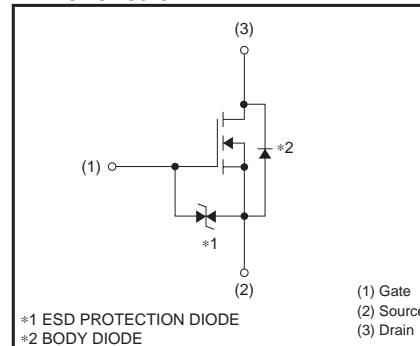
Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-a)*	125	°C / W

\* When mounted on a ceramic board

●Dimensions (Unit : mm)



### ● Inner circuit





## ● Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	—	—	±10	μA	V <sub>GS</sub> = ±12V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	45	—	—	V	I <sub>D</sub> = 1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	—	—	1	μA	V <sub>DS</sub> = 45V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	0.5	—	1.5	V	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA
Static drain-source on-state resistance	R <sub>DS(on)*</sub>	—	95	130	mΩ	I <sub>D</sub> = 2.5A, V <sub>GS</sub> = 4.5V
		—	100	140	mΩ	I <sub>D</sub> = 2.5A, V <sub>GS</sub> = 4V
		—	125	175	mΩ	I <sub>D</sub> = 2.5A, V <sub>GS</sub> = 2.5V
Forward transfer admittance	Y <sub>fs</sub>   *	2.0	—	—	S	V <sub>DS</sub> = 10V, I <sub>D</sub> = 2.5A
Input capacitance	C <sub>iss</sub>	—	250	—	pF	V <sub>DS</sub> = 10V
Output capacitance	C <sub>oss</sub>	—	60	—	pF	V <sub>GS</sub> = 0V
Reverse transfer capacitance	C <sub>rss</sub>	—	30	—	pF	f=1MHz
Turn-on delay time	t <sub>d(on)*</sub>	—	9	—	ns	V <sub>DD</sub> = 25V I <sub>D</sub> = 1.2A V <sub>GS</sub> = 4.5V
Rise time	t <sub>r</sub> *	—	15	—	ns	R <sub>L</sub> = 20.8Ω
Turn-off delay time	t <sub>d(off)*</sub>	—	20	—	ns	R <sub>G</sub> =10Ω
Fall time	t <sub>f</sub> *	—	14	—	ns	
Total gate charge	Q <sub>g</sub> *	—	3.2	—	nC	V <sub>DD</sub> = 25V I <sub>D</sub> = 2.5A
Gate-source charge	Q <sub>gs</sub> *	—	0.9	—	nC	V <sub>GS</sub> = 4.5V
Gate-drain charge	Q <sub>gd</sub> *	—	0.7	—	nC	R <sub>L</sub> = 10Ω R <sub>G</sub> =10Ω

\*Pulsed

## ● Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	—	—	1.2	V	I <sub>S</sub> = 2.5A, V <sub>GS</sub> =0V

\*Pulsed